

Application No. 10/679,394
Amendment dated November 2, 2006
Reply to Office Action of August 2, 2006

Docket No.: 0941-0854P

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NOV 02 2006**AMENDMENTS TO THE CLAIMS**

1. (Currently Amended) A method of encapsulating a display element, comprising steps of:

providing an organic light emitting diode or a plastic light emitting diode, comprising a luminescent body formed on a glass substrate and a glass cap with a rib structure formed on the bottom surface thereof;

coating a sealing layer of frit on the rim of the glass cap and surrounding the rib structure;

providing a pedestal on an outer side of the glass substrate~~which the display element is placed;~~

providing a pressing plate ~~disposed on the glass cap display element;~~

providing a high-power beam penetrating the glass cap to focus on the sealing layer so as to sinter the frit; and

applying pressure on the pedestal and the pressing plate;

wherein at least one of the pressing plate and the pedestal is of metal materials with good thermal conductivity, such that the pressing plate and/or the pedestal sink the heat generated from sintering the frit.

2. (Canceled)

3. (Original) The method of encapsulating a display element according to claim 1, wherein the high-power beam is a laser beam.

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4. (Original) The method of encapsulating a display element according to claim 1, wherein the laser beam has a wavelength exceeding 550 nm.
5. (Original) The method of encapsulating a display element according to claim 1, wherein the high-power beam is an infrared ray.
6. (Original) The method of encapsulating a display element according to claim 1, wherein the infrared ray has a wavelength exceeding 800 nm.
7. (Original) The method of encapsulating a display element according to claim 1, wherein the rib structure is frit.
8. (Original) The method of encapsulating a display element according to claim 1, wherein the rib structure is of ceramic materials.
9. (Original) The method of encapsulating a display element according to claim 1, wherein the luminescent body is laminated with at least an anode layer, an organic luminescent layer and a cathode layer.
10. (New) The method of encapsulating a display element according to claim 1, wherein the pressing plate and the pedestal are formed of copper.

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11. (New) A method of encapsulating a display element, comprising steps of:

providing an organic light emitting diode or a plastic light emitting diode, comprising a luminescent body formed on a glass substrate, and a glass cap;

forming a rib structure on a bottom surface of the glass cap, surrounding the organic light emitting diode or the plastic light emitting diode;

coating a sealing layer of frit on the rim of the glass cap and surrounding the rib structure after forming the rib structure;

combining the glass substrate and the glass cap with a gap therebetween defined by the rib structure;

providing a pedestal on an outer side of the glass substrate;

providing a pressing plate on the glass cap;

providing a high-power beam penetrating the glass cap to focus on the sealing layer so as to sinter the frit; and

applying pressure on the pedestal and the pressing plate.

12. (New) The method of encapsulating a display element according to claim 11, wherein the rib structure is continuous.